

PATENT NUMBER

U.S. UTILITY Patent Application

TyB O.I.P.E. SCANNED KGB O.A. TC	PATENT DATE
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APPLICATION NO. 09/843924	CONT/PRIOR F	CLASS 257 438	SUBCLASS 613 737	ART UNIT 128 2826	EXAMINER LWRS None
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APPLICANTS
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TITLE
Method for forming bump, semiconductor device and method for making the same, circuit board, and electronic device

ISSUING CLASSIFICATION									
ORIGINAL				CROSS REFERENCE(S)					
CLASS		SUBCLASS		CLASS		SUBCLASS (ONE SUBCLASS PER BLOCK)			
INTERNATIONAL CLASSIFICATION									
0									

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____	_____ (Primary Examiner) _____ (Date)			ISSUE FEE	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)			ISSUE BATCH NUMBER	
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